

Saves process time

Excellent fillability for narrow gap/pitch

Low warpage

Applications

IC Package/Mobile

Advanced IC Packages (Flip-chip package such as FC-CSP, FC-SiP module)

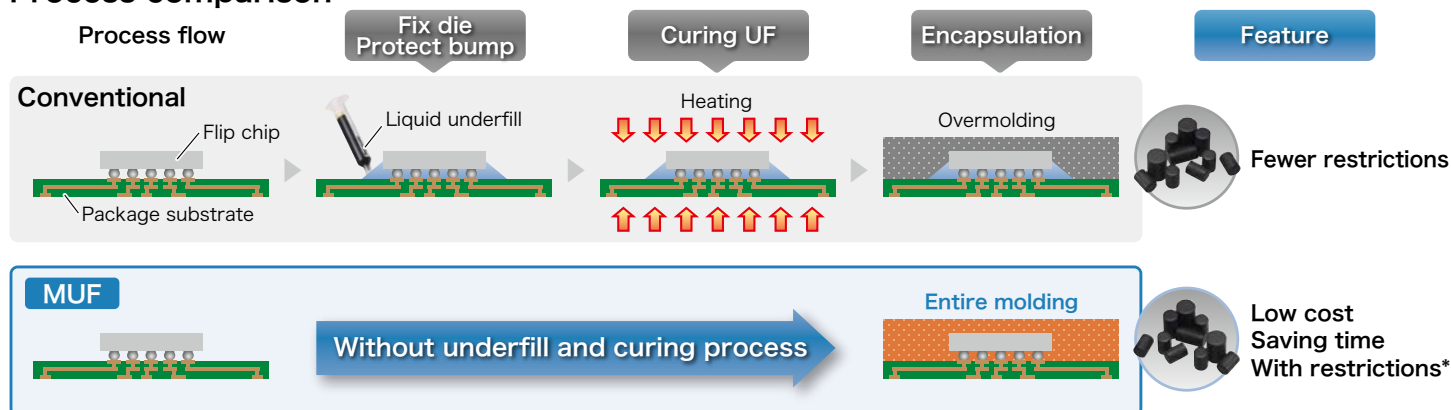
LEXCM^{CF}

CV8581 CV8713

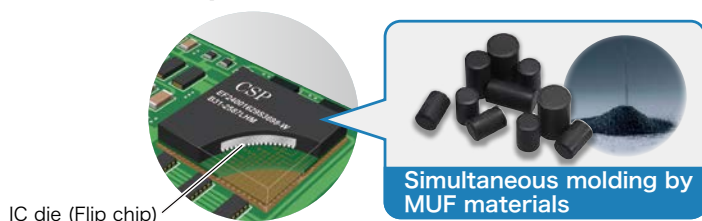
Molded underfill (MUF) semiconductor encapsulation molding compounds

MUF technology is a process that can fill the narrow gap under the flip-chip without voids and overmold the die in one-step. Panasonic Industry proprietary high filler loading and resin design technologies are the features of this material.

Process comparison

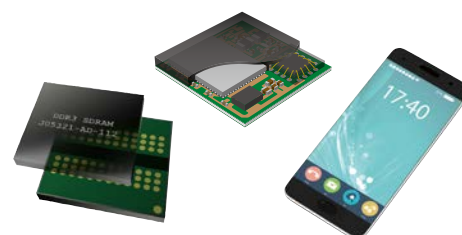


Excellent fillability for narrow gap and narrow pitch



Application

Flip-chip package
- FC-CSP
- FC-SiP module
Other



We have various options of MUF materials proven for many packages. Please contact us.

General properties

Item	Unit	LEXCM ^{CF}			
		CV8581MUW	CV8713UB	CV8714AHSL	X8770UY
Tg (TMA)	°C	170	145	153	150
CTE 1	ppm/°C	20	9	12	9
CTE 2		64	38	47	40
Flexural modulus (25°C)	GPa	16	24	23	26
Filler size (Max)	μm	20	20	10	20
Mold shrinkage	%	0.32	0.20	0.21	0.20

Please see our website for Notes before you use.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry CV8581

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